

IN THE SPECIFICATION

Please amend the paragraph [00027] at page 8 as follows:

In an alternate embodiment, a heat conducting element 110 is also configured to receive heat from the substrate 35 through focus ring 60. In such an embodiment, heat conducting contact is made from the substrate 35 to the cap 100 of the focus ring 60 by means of the heat conducting element 110 and focus ring 60 contacting both the substrate 35 and the cap 100. As seen in FIG. 2, the heat conducting element 110 includes a first segment 110A extending along and in contact with the cap 100, and a second segment 110B extending substantially perpendicular to the first segment 110A. The second segment 110B is configured to contact the focus ring 60 and a surface of the substrate holder 30 when the shield ring is coupled to the substrate holder assembly. The second segment 110B also includes a protrusion 110C extending substantially perpendicular from the second segment so as to provide a discrete surface for contacting the substrate holder surface.